

## Poster Session

P001	Monitoring method of residual stress in a substrate during thin film processing K.Nakahira, H.Tago, H.Kishi, K.Suzuki, H.Miura, Tohoku University / Japan
P002	Direct Copper Electrodeposition on High Resistivity substrates from Ethylenediamine Complex bath H.Arimura <sup>1,2</sup> , <sup>1</sup> Konan University, <sup>2</sup> Ishihara Chemical / Japan
P003	All-Wet Cu-TSV Fabrication Process Using Electroless Barrier and Seed Layers R.Arima <sup>1</sup> , F.Inoue <sup>1</sup> , T.Yokoyama <sup>1</sup> , H.Miyake <sup>1</sup> , S.Tanaka <sup>2</sup> , T.Terui <sup>2</sup> , T.Shimizu <sup>1</sup> , S.Shingubara <sup>1</sup> , <sup>1</sup> Kansai University, <sup>2</sup> National Institute of Information and Communication Technology / Japan
P004	Adsorption and desorption kinetic study of organic additives during copper electrodeposition by microfluidic reactor Y.Miyamoto, S.Hattori, N.Okamoto, T.Saito, K.Kondo, Osaka Prefecture University / Japan
P005	Stress-induced migration of the electroplated copper thin film interconnection N.Saito, N.Murata, K.Tamakawa, K.Suzuki, H.Miura, Tohoku University / Japan
P006	Modeling the process window of Bond Line Thickness for Printable Die Attach Adhesives in DRAM wBGA packaging C.H.Lu, W.F.Chang, Powerchip Technology / Taiwan, R.O.C.
P007	Effects of Laser Irradiation Conditions on Bonding Characteristics of Lead-free Solder Joints by Laser Soldering N.Iwata, Osaka University / Japan
P033	Characterization of surface oxide of lead-free solder particle by TEM and STEM X.Luo <sup>1,2</sup> , X.Lu <sup>2</sup> , W.Du <sup>2</sup> , T.Yamaguchi <sup>3</sup> , J.Gavin <sup>3</sup> , J.Liu <sup>1,2</sup> , <sup>1</sup> Chalmers University of Technology, <sup>2</sup> Shanghai University, <sup>3</sup> Henkel Technologies, Sweden / P.R.China
P008	Reliability Evaluation for Cell Bonding in Slat-type Soler Module N.Atsuta, Toray Engineering / Japan
P009	Effect of Learning Pseudo Defective Samples Generated with Charactaristic Vector in Neuro Visual Inspection System N.Nakashima, Osaka University / Japan
P010	Effect of thermal/humidity stress on the reliability of high power blue LEDs S.Zhou <sup>1</sup> , Q.Zhang <sup>2</sup> , S.Liu <sup>1,2</sup> , <sup>1</sup> Shanghai Jiao Tong University, <sup>2</sup> Huazhong University of Science & Technology / China
P011	Simulation and Experiments on the Performance of LED under Temperature Shock X.Gui <sup>1,2</sup> , X.Luo <sup>1,2</sup> , S.Liu <sup>1,2</sup> , <sup>1</sup> Wuhan National Laboratory for Optoelectronics, <sup>2</sup> Huazhong University of Science & Technology / China
P012	Wavelength Addressing Optical Interconnection Using Plug-in Alignment with A Multi-Way Optical Socket K.Nakama, Tokai University / Japan
P014	A study of Cable Failure Diagnosis Using TDR T.Kuwahara, Mitsubishi Electric / Japan
P015	A Low Power Consumption QVCO Design for RF Package Effect Validating S.M.Wu, R.S.Huang, B.H.Yu, National University of Kaohsiung / Taiwan, R.O.C.
P016	Novel Substrate Design Kit with Power Delivery System Resonant for RF Package Signal Integrity S.M.Wu, M.H.Li, C.T.Kuo, National University of Kaohsiung / Taiwan, R.O.C.
P017	An Experimental Study of Planar-scanning Near-field to Far-field Transformation using a Dipole Zntenna T.Watanabe <sup>1</sup> , J.Ochiai <sup>1</sup> , K.Takizawa <sup>2</sup> , H.Kurihara <sup>2</sup> , O.Hashimoto <sup>1</sup> , <sup>1</sup> Aoyama Gakuin University, <sup>2</sup> TDK-EPC / Japan

## Poster Session

P018	Study on Hierachal Optimization Method in Design of System LSI T.Yasumura, Osaka University / Japan
P019	Quic Changeover Approach Test Handler C.S.Chew, N.R.Subramanian, Intel Technology / Malaysia
P020	Deposition of copper particles onto porous silicon: Morphological transformation from cube to spherical shape particles M.A.Bakar, S.Yaakob, W.L.Tan, J.Ismail, K.Ibrahim, University Sains Malaysia / Malaysia
P021	Thermal behaviour and kinetic study of the thermal degradation of ENR-based W.L.Tan, M.A.Bakar, University Sains Malaysia / Malaysia
P022	Electrical and thermal conductivities of thermally conductive adhesives composed of a multi-functional epoxy resin containing Cu fillers coated with Ag M.Inoue <sup>1</sup> , H.Muta <sup>1</sup> , S.Yamanaka <sup>1</sup> , J.Liu <sup>2,3</sup> , <sup>1</sup> Osaka University, <sup>2</sup> Chalmers University of Technology, <sup>3</sup> Shanghai University / Japan, Sweden, China
P023	Using wet etching process and electroless nickel plating process to fabricate CMOS-MEMS probe chip K.Y.Lee, J.T.Huang, H.J.Hsu, C.K.Chen, T.C.Tsai, National Taipei University of Technology / Taiwan, R.O.C.
P024	Electroformed Printing Pins H.J.Hsu, J.T.Huang, K.Y.Lee, T.C.Tsai, National Taipei University of Technology / Taiwan, R.O.C.
P025	Three-dimensionnal Micro Fluidics Device Using Contrifgal Force T.Azeta <sup>1</sup> , Y.Ukita <sup>2</sup> , H.Nose <sup>1</sup> , S.Kondo <sup>1</sup> , Y.Utsumi <sup>1</sup> , <sup>1</sup> University of Hyogo, <sup>2</sup> Japan Advanced Institute of Science and Technology / Japan
P026	High-sensitive enzyme-linked immunosorbent assay in three-dimensional lab-on -a T.Azeta <sup>1</sup> , Y.Ukita <sup>2</sup> , H.Nose <sup>1</sup> , S.Kondo <sup>1</sup> , Y.Utsumi <sup>1</sup> , <sup>1</sup> University of Hyogo, <sup>2</sup> Japan Advanced Institute of Science and Technology / Japan
P027	High-Sensitive Detection of Polychlorinated Biphenyl on Three-Dimensional Lab-on-a H.Nose <sup>1</sup> , T.Azeta <sup>1</sup> , Y.Ukita <sup>2</sup> , S.Kondo <sup>1</sup> , C.Kataoka <sup>3</sup> , Y.Utsumi <sup>1</sup> , <sup>1</sup> University of Hyogo, <sup>2</sup> Japan Advanced Institute of Science and Technology, <sup>3</sup> Carbuncle Bioscientech / Japan
P028	Proposal of stacked electrodesfor multiplex neural interface M.Yoshida, University of Hyogo / Japan
P029	A biochip using antibody-covered magnetic particles to detect the concentration and antibiotics resistance of specific bacteria J.T.Huang, C.C.Hsieh, G.C.Wang, National Taipei University of Technology / Taiwan, R.O.C.
P030	Blood vessel pressure sensor measurement using the CMOS-MEMS technique J.T.Huang, H.R.Jan, National Taipei University of Technology / Taiwan, R.O.C.
P031	Study and Development on the Flexible Pressure-sensor Composed of Nano composite Materials J.T.Huang, C.C.Cheng, S.C.Lan, National Taipei University of Technology / Taiwan, R.O.C.
P032	Mechanical and Electrical Properties of Self-Restoring Sheet Materials for Stretchable N.Sekido, K.Yasuda, O.Takai, Nagoya University / Japan